

## <A740 / <A740F 400V N-Channel MOSFET

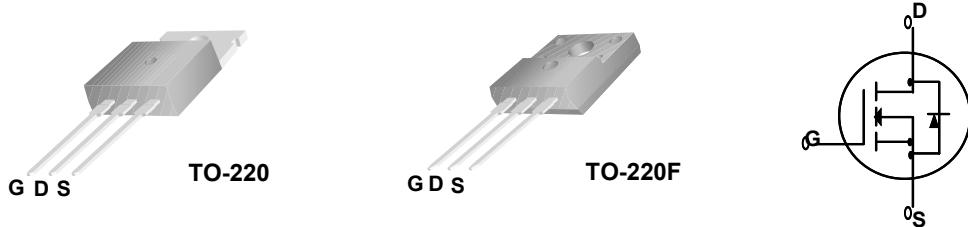
### General Description

This Power MOSFET is produced using SL semi's advanced planar stripe DMOS technology.

This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficiency switched mode power supplies, active power factor correction based on half bridge topology.

### Features

- 10.5A, 400V,  $R_{DS(on)} = 0.55\Omega$  @  $V_{GS} = 10$  V
- Low gate charge ( typical 30nC)
- Fast switching
- 100% avalanche tested
- Improved dv/dt capability



### Absolute Maximum Ratings

$T_C = 25^\circ\text{C}$  unless otherwise noted

Symbol	Parameter	HM740	HM740F	Units
$V_{DSS}$	Drain-Source Voltage	400		V
$I_D$	Drain Current - Continuous ( $T_C = 25^\circ\text{C}$ )	10.5	10.5*	A
	- Continuous ( $T_C = 100^\circ\text{C}$ )	6.6	6.6 *	A
$I_{DM}$	Drain Current - Pulsed	(Note 1)	42	A
$V_{GSS}$	Gate-Source Voltage		$\pm 30$	V
$E_{AS}$	Single Pulsed Avalanche Energy	(Note 2)	378	mJ
$E_{AR}$	Repetitive Avalanche Energy	(Note 1)	13.9	mJ
$dv/dt$	Peak Diode Recovery $dv/dt$	(Note 3)	4.5	V/ns
$P_D$	Power Dissipation ( $T_C = 25^\circ\text{C}$ )	139	45.5	W
	- Derate above $25^\circ\text{C}$	1.11	0.36	W/ $^\circ\text{C}$
$T_J, T_{STG}$	Operating and Storage Temperature Range		-55 to +150	$^\circ\text{C}$
$T_L$	Maximum lead temperature for soldering purposes, 1/8" from case for 5 seconds		300	$^\circ\text{C}$

\* Drain current limited by maximum junction temperature.

### Thermal Characteristics

Symbol	Parameter	HM740	HM740F	Units
$R_{\theta JC}$	Thermal Resistance, Junction-to-Case	0.90	2.75	$^\circ\text{C}/\text{W}$
$R_{\theta CS}$	Thermal Resistance, Case-to-Sink Typ.	0.5	--	$^\circ\text{C}/\text{W}$
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient	62.5	62.5	$^\circ\text{C}/\text{W}$

## **Electrical Characteristics**

$T_C = 25^\circ\text{C}$  unless otherwise noted

Symbol	Parameter	Test Conditions	Min	Typ	Max	Units
<b>Off Characteristics</b>						
$BV_{DSS}$	Drain-Source Breakdown Voltage	$V_{GS} = 0 \text{ V}$ , $I_D = 250 \mu\text{A}$	400	--	--	V
$\Delta BV_{DSS} / \Delta T_J$	Breakdown Voltage Temperature Coefficient	$I_D = 250 \mu\text{A}$ , Referenced to 25°C	--	0.6	--	V/°C
$I_{DSS}$	Zero Gate Voltage Drain Current	$V_{DS} = 400 \text{ V}$ , $V_{GS} = 0 \text{ V}$	--	--	1	$\mu\text{A}$
		$V_{DS} = 320 \text{ V}$ , $T_C = 125^\circ\text{C}$	--	--	10	$\mu\text{A}$
$I_{GSSF}$	Gate-Body Leakage Current, Forward	$V_{GS} = 30 \text{ V}$ , $V_{DS} = 0 \text{ V}$	--	--	100	nA
$I_{GSSR}$	Gate-Body Leakage Current, Reverse	$V_{GS} = -30 \text{ V}$ , $V_{DS} = 0 \text{ V}$	--	--	-100	nA

## On Characteristics

$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_D = 250 \mu A$	2.0	--	4.0	V
$R_{DS(on)}$	Static Drain-Source On-Resistance	$V_{GS} = 10 V, I_D = 5.25 A$	--	0.43	0.55	$\Omega$

## Dynamic Characteristics

$C_{iss}$	Input Capacitance	$V_{DS} = 25 \text{ V}, V_{GS} = 0 \text{ V},$ $f = 1.0 \text{ MHz}$	--	870	--	pF
$C_{oss}$	Output Capacitance		--	250	--	pF
$C_{rss}$	Reverse Transfer Capacitance		--	85	--	pF

## Switching Characteristics

$t_{d(on)}$	Turn-On Delay Time	$V_{DD} = 200 \text{ V}$ , $I_D = 10.5\text{A}$ , $R_G = 25 \Omega$ (Note 4, 5)	--	15	--	ns
$t_r$	Turn-On Rise Time		--	90	--	ns
$t_{d(off)}$	Turn-Off Delay Time		--	80	--	ns
$t_f$	Turn-Off Fall Time		--	80	--	ns
$Q_g$	Total Gate Charge	$V_{DS} = 320 \text{ V}$ , $I_D = 10.5 \text{ A}$ , $V_{GS} = 10 \text{ V}$ (Note 4, 5)	--	30	-	nC
$Q_{gs}$	Gate-Source Charge		--	4.0	--	nC
$Q_{gd}$	Gate-Drain Charge		--	15	--	nC

## Drain-Source Diode Characteristics and Maximum Ratings

$I_S$	Maximum Continuous Drain-Source Diode Forward Current		--	--	10.5	A
$I_{SM}$	Maximum Pulsed Drain-Source Diode Forward Current		--	--	42.0	A
$V_{SD}$	Drain-Source Diode Forward Voltage		$V_{GS} = 0 \text{ V}$ , $I_S = 10.5 \text{ A}$	--	--	1.5
$t_{rr}$	Reverse Recovery Time		$V_{GS} = 0 \text{ V}$ , $I_S = 10.5 \text{ A}$ ,	--	300	--
$Q_{rr}$	Reverse Recovery Charge		$dI_F / dt = 100 \text{ A}/\mu\text{s}$	(Note 4)	--	2.5
					--	$\mu\text{C}$

#### **Notes:**

1. Repetitive Rating : Pulse width limited by maximum junction temperature
  2.  $L = 6\text{ mH}$ ,  $I_{AS} = 10.5\text{ A}$ ,  $V_{DD} = 50\text{ V}$ ,  $R_G = 25\Omega$ , Starting  $T_J = 25^\circ\text{C}$
  3.  $I_{SD} \leq 10.5\text{ A}$ ,  $dI/dt \leq 2000\text{ A}/\mu\text{s}$ ,  $V_{DD} \leq V_{BDSS}$  Starting  $T_J = 25^\circ\text{C}$
  4. Pulse Test : Pulse width  $\leq 300\mu\text{s}$ . Duty cycle  $\leq 2\%$
  5. Essentially independent of operating temperature

### Typical Characteristics

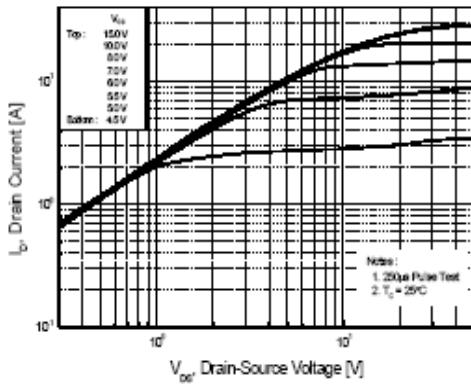


Figure 1. On-Region Characteristics

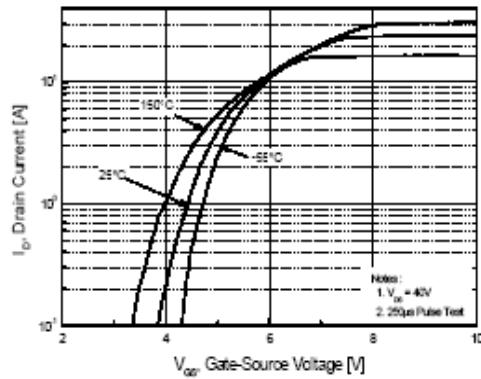


Figure 2. Transfer Characteristics

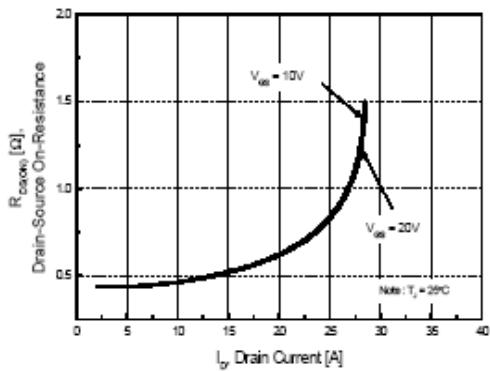


Figure 3. On-Resistance Variation vs  
Drain Current and Gate Voltage

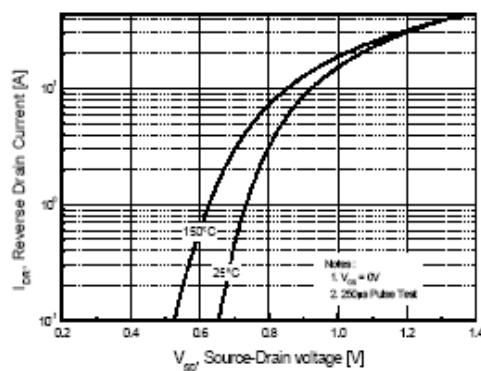


Figure 4. Body Diode Forward Voltage  
Variation with Source Current  
and Temperature

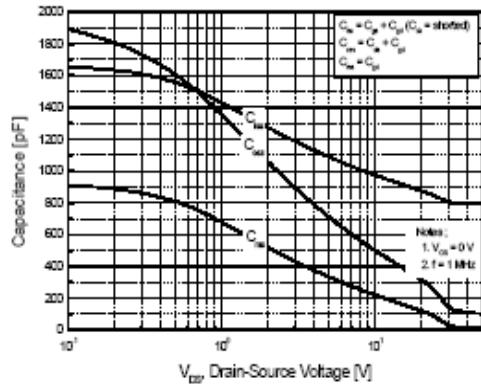


Figure 5. Capacitance Characteristics

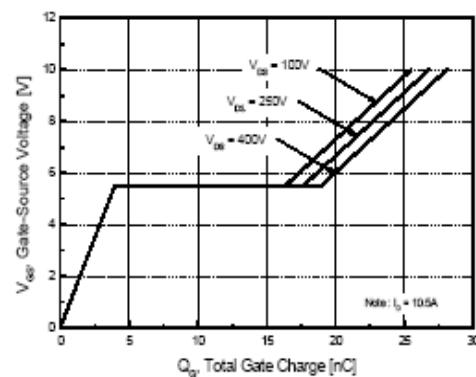
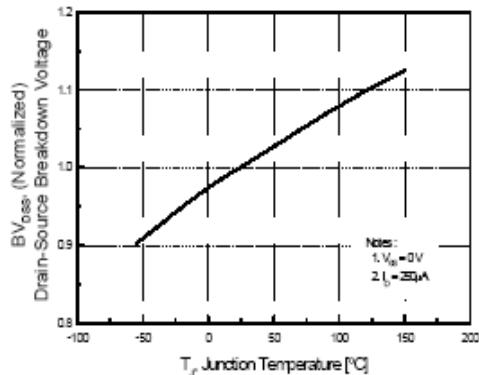
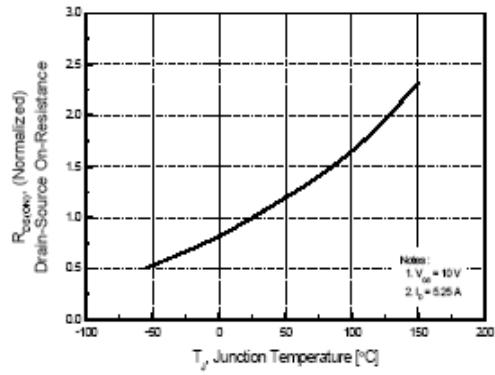


Figure 6. Gate Charge Characteristics

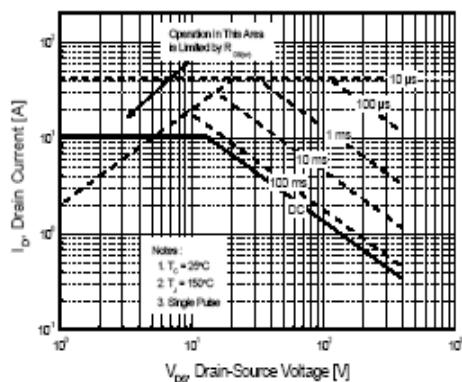
**Typical Characteristics** (Continued)



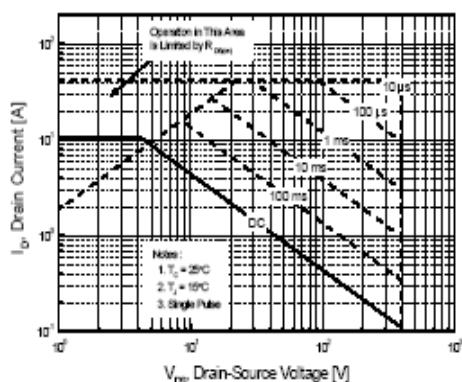
**Figure 7. Breakdown Voltage Variation  
vs Temperature**



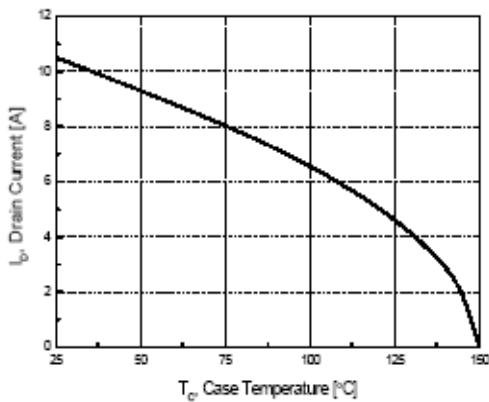
**Figure 8. On-Resistance Variation  
vs Temperature**



**Figure 9-1. Maximum Safe Operating Area  
for HM740**



**Figure 9-2. Maximum Safe Operating Area  
for HM740F**



**Figure 10. Maximum Drain Current  
vs Case Temperature**

Typical Characteristics

(Continued)

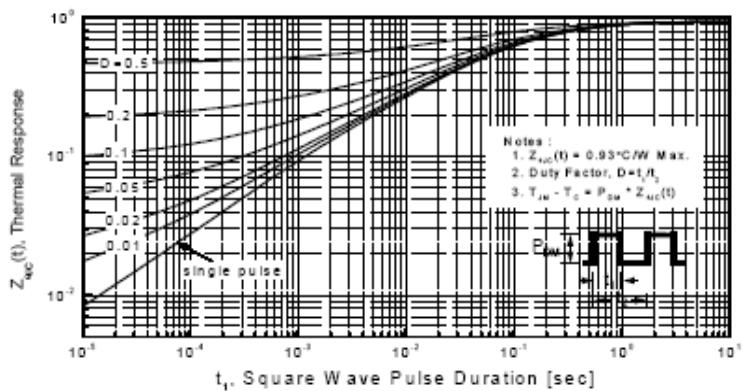


Figure 11-1. Transient Thermal Response Curve  
for HM740

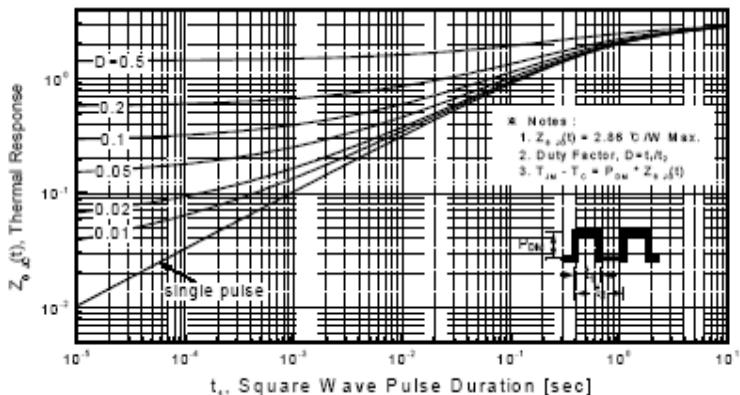
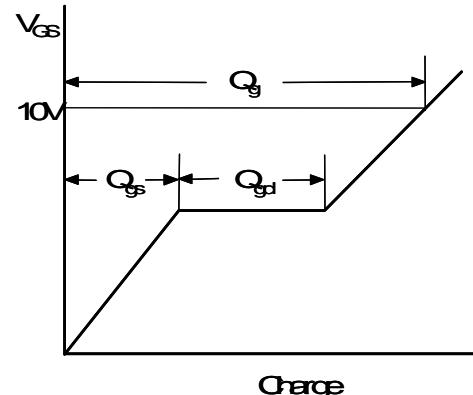
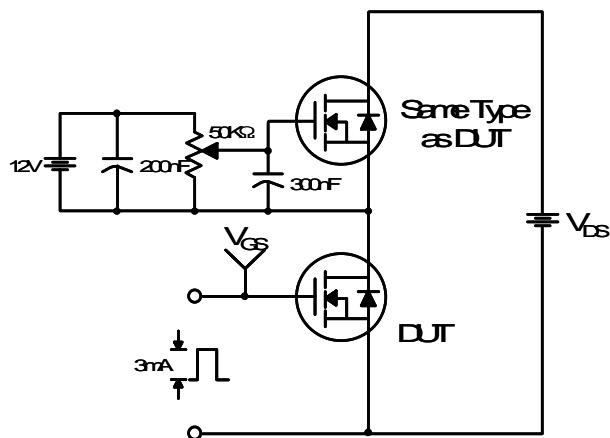
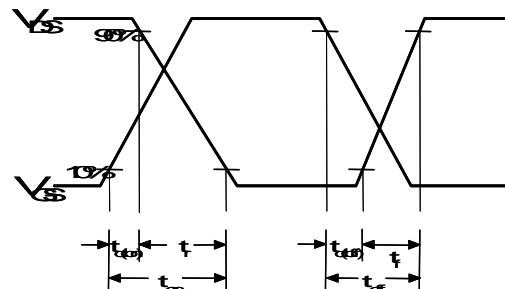
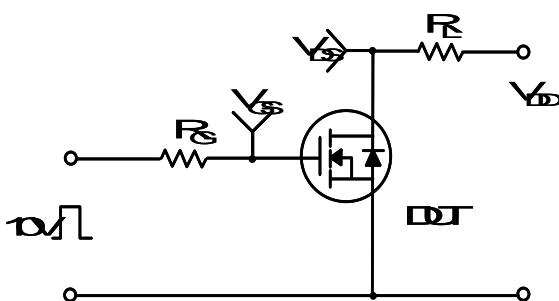


Figure 11-2. Transient Thermal Response Curve  
for HM740F

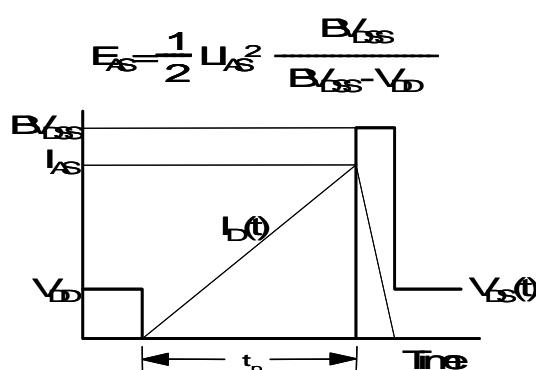
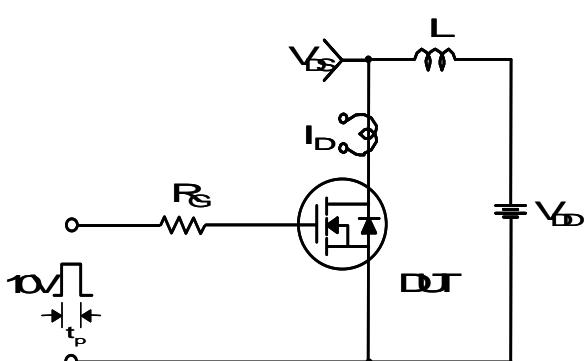
Gate Charge Test Circuit & Waveform



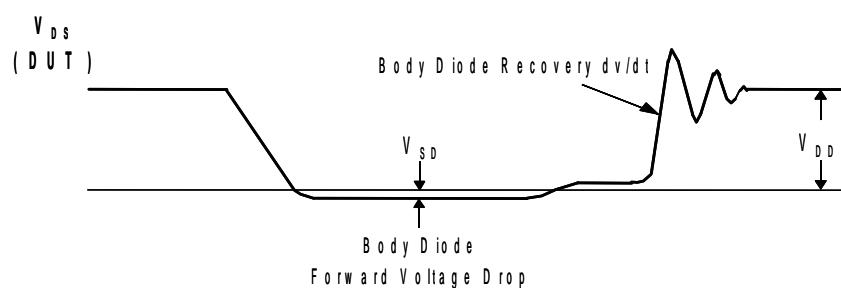
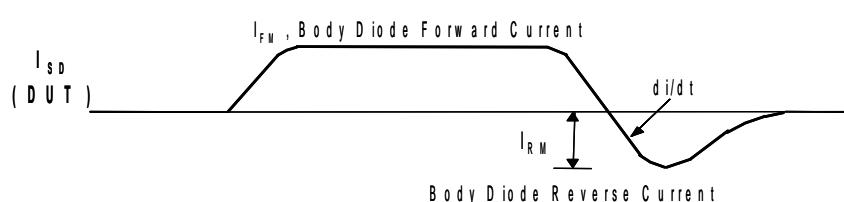
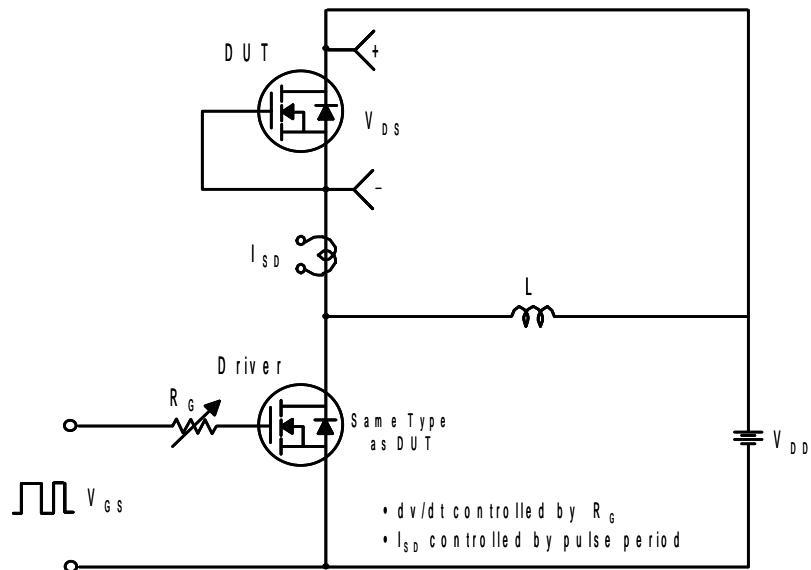
Resistive Switching Test Circuit & Waveforms



Unclamped Inductive Switching Test Circuit & Waveforms



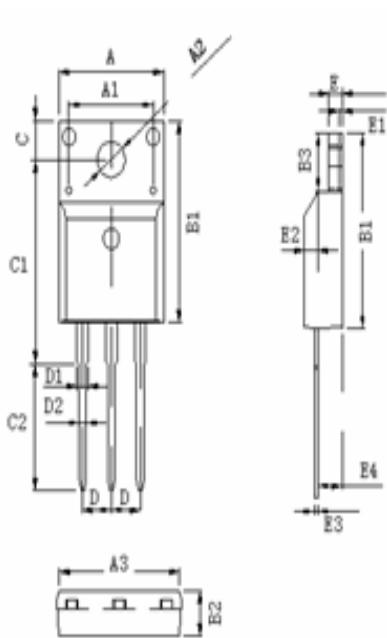
Peak Diode Recovery dv/dt Test Circuit & Waveforms



## Package Dimensions

TO-220F

### TO-220F 外形尺寸图



DIM.	MILLIMETERS
A	10.03 ± 0.20
A1	7.00
A2	3.12 ± 0.10
A3	9.70 ± 0.20
B1	15.75 ± 0.20
B2	4.72 ± 0.20
B3	6.70 ± 0.20
C	3.30 ± 0.10
C1	15.80 ± 0.20
C2	9.80 ± 0.2
D	Typical 2.54
D1	1.47 (MAX)
D2	0.80 ± 0.10
E	2.55 ± 0.20
E1	0.70
E2	1.00 × 45°
E3	0.50
E4	2.80 ± 0.20